




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L072CZU6	S3MI*447XXXZ	A	998Z	2020-07-02
	Amount	UoM	Unit type	ST ECOPACK Grade
	103.18	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	No lead	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	S3MI*447XXXZ				6000000.0	1000007.2
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	3.832	mg	supplier	die	Silicon (Si)	7440-21-3		3.527	mg	920407	34183
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	7046	262
				supplier	metallization	Copper (Cu)	7440-50-8		0.088	mg	22965	853
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.010	mg	2610	97
				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	3392	126
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	261	10
				supplier	Passivation	Silicon Nitride	12033-89-5		0.024	mg	6263	233
				supplier	Passivation	Silicon Oxide	7631-86-9		0.142	mg	37056	1376
Glue Epoxy_EN4900GC_MUSASHI	M-011 Other inorganic materials	1.303	mg	Supplier	Metals	Silver	7440-22-4		1.056	mg	810000	10230
				Supplier	Organic Compounds	Acrylic resin	Trade Secret		0.085	mg	65000	821
				Supplier	Organic Compounds	Polybutadiene derivative	Trade Secret		0.052	mg	40000	505
				Supplier	Organic Compounds	Epoxy resin	Trade Secret		0.033	mg	25000	316
				Supplier	Organic Compounds	Butadiene copolymer	Trade Secret		0.013	mg	10000	126
				Supplier	Organic Compounds	Acrylate	Trade Secret		0.046	mg	35000	442
				Supplier	Organic Compounds	Peroxide	Trade Secret		0.007	mg	5000	63
				Supplier	Metallic compounds	Additive	Trade Secret		0.013	mg	10000	126
Encapsulation_EME-G770_Sumitomo	M-011 Other inorganic materials	34.927	mg	Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		0.733	mg	21000	7109
				Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		0.733	mg	21000	7109
				Supplier	Plastics/polymers	Phenol Resin A	Trade Secret		0.733	mg	21000	7109
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		27.259	mg	780450	264187
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		4.028	mg	115320	39036
				Supplier	Non-metals	Carbon Black	1333-86-4		0.218	mg	6230	2109
				Supplier	Plastics/polymers	Metal Hydroxide	Trade Secret		0.489	mg	14000	4739
				Supplier	Metals	Phenol Resin B	Trade Secret		0.733	mg	21000	7109
Wire_AG SI TYPE_MKE	Bonding Wire	0.353	mg	Supplier	Metals	Silver	7440-22-4		0.339	mg	960000	3284
				Supplier	Metals	Gold	7440-57-5		0.002	mg	5000	17
				Supplier	Metals	Palladium	7440-05-3		0.011	mg	30000	103
				Supplier	Metals	Platinum	7440-06-4		0.002	mg	5000	17
Plating anode_Pure Tin_ASAHI	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	10452
Leadframe_C7025+AG_HDS	Copper & its alloys	61.687	mg	Supplier	Metals	Copper	7440-50-8		56.576	mg	917140	548321
				Supplier	Metals	Nickel	7440-02-0		1.295	mg	21000	12555
				Supplier	Glass	Silicon	7440-21-3		0.075	mg	1210	723
				Supplier	Metals	Magnesium	7439-95-4		0.071	mg	1150	688
				Supplier	Metals	Silver	7440-22-4		3.670	mg	59500	35573